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GB/T 8750-2014

Gold bonding wire for semiconductor package

半导体封装用键合金丝

(English Translation)

Issued on: July 24, 2014 **Implemented on: February 1, 2015**

Issued by: General Administration of Quality Supervision, Inspection and Quarantine of the People's Republic of China;
Standardization Administration of China

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Document data

1 Document data

Sector: National standard (Recommended).

Issuing body: General Administration of Quality Supervision, Inspection and Quarantine of the People's Republic of China; Standardization Administration of China.

Date of issue: 2014-07-24.

Date of implementation: 2015-02-01.

Status: obsolete, replaced by GB/T 8750-2022.

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